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- Output Ports Have 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OLV} (Output Undershoot)
 < 0.5 V at V_{CC} = 5 V, T_A = 25°C
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and DIPs (JT)

description

These 11-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

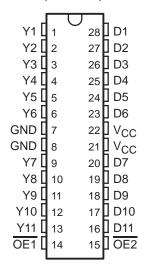
The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all 11 outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include $25-\Omega$ series resistors to reduce overshoot and undershoot.

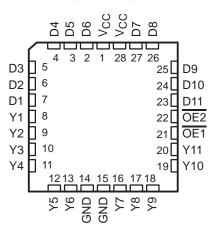
To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT5400 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ABT5400 is characterized for operation from -40° C to 85° C.

SN54ABT5400 ... JT PACKAGE SN74ABT5400 ... DW PACKAGE (TOP VIEW)



SN54ABT5400 . . . FK PACKAGE (TOP VIEW)



FUNCTION TABLE

	INPUTS	OUTPUT	
OE1	OE2	D	Y
L	L	L	L
L	L	Н	Н
Н	X	Χ	Z
Х	Н	Χ	Z

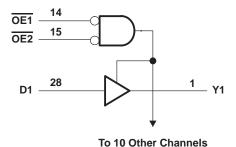
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logic symbol†

& 14 OE1 ΕN 15 OE2 28 1 D1 1 ∇ **Y1** 27 2 D2 **Y2** 26 3 D3 **Y3** 25 4 D4 **Y4** 24 5 D5 **Y5** 23 6 D6 **Y6** 20 9 D7 **Y7** 19 10 **D8 Y8** 18 11 **Y9** D9 17 12 D10 Y10 16 13 D11 Y11

logic diagram (positive logic)



Pin numbers shown are for the DW and JT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO	. -0.5 V to 5.5 V
Current into any output in the low state, I _O	30 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2): DW package	1.2 W
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

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recommended operating conditions (see Note 2)

				3T5400	SN74ABT5400			
					MIN	MAX	UNIT	
VCC	4.5	5.5	4.5	5.5	V			
VIH	High-level input voltage	2	FW	2		V		
V _{IL} Low-level input voltage				0.8		0.8	V	
V _I Input voltage				Vcc	0	VCC	V	
I _{OH} High-level output current				-12		-12	mA	
I _{OL} Low-level output current				12		12	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	PAC.	10		10	ns/V	
T _A Operating free-air temperature			-55	125	-40	85	°C	

NOTE 3: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TER TEST CONDITIONS -			T _A = 25°C			SN54ABT5400		SN74ABT5400		
PARAMETER				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$		3.35	3.7		3.3		3.35		
Maria	$V_{CC} = 5 \text{ V}, \qquad I_{OH} = -1 \text{ mA}$			3.85	4.2		3.8		3.85		
VOH	V 45V	$I_{OH} = -3 \text{ mA}$					3		3.1		V
	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$		2.6					2.6		
Va.	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OL} = 8 \text{ mA}$						0.8		0.65	V
V _{OL}	V _{CC} = 4.5 V	$I_{OL} = 12 \text{ mA}$								0.8	V
lį	$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GN	ID			±1		±1		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V},$	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$				50		50		50	μΑ
lozL	$V_{CC} = 5.5 V$,	$V_{CC} = 5.5 \text{ V}, V_{O} = 0.5 \text{ V}$				-50		-50		-50	μΑ
l _{off}	$V_{CC} = 0$,	$V_{CC} = 0$, $V_I \text{ or } V_O \le 4.5 \text{ V}$				±100	4	27		±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 \text{ V}$	Outputs high			50	5	50		50	μΑ
lo	$V_{CC} = 5.5 \text{ V},$	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.5 \text{ V}$		-25	-45	-100	-25	-100	-25	-100	mA
los‡	$V_{CC} = 5.5 V$,	$V_O = 0$		-50		-200	50	-200	-50	-200	mA
	.,		Outputs high		5	50	y	50		50	μΑ
ICC	$V_{CC} = 5.5 \text{ V}, I_{O} = 0$ $V_{I} = V_{CC} \text{ or GND}$		Outputs low		36	45		45		45	mA
	1, 100 0. 0.		Outputs disabled		1	50		50		50	μΑ
	$V_{CC} = 5.5 \text{ V},$ One input at	Data innuta	Outputs enabled			1.5		1.5		1.5	
ΔlCC§	3.4 V, Other	Other	Outputs disabled			0.05		0.05		0.05	mA
	inputs at VCC or GND Control inputs					1.5		1.5		1.5	
Ci	V _I = 2.5 V or 0.5 V				3						pF
Co	V _O = 2.5 V or 0.5 V				8						pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

SN54ABT5400, SN74ABT5400 11-BIT LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

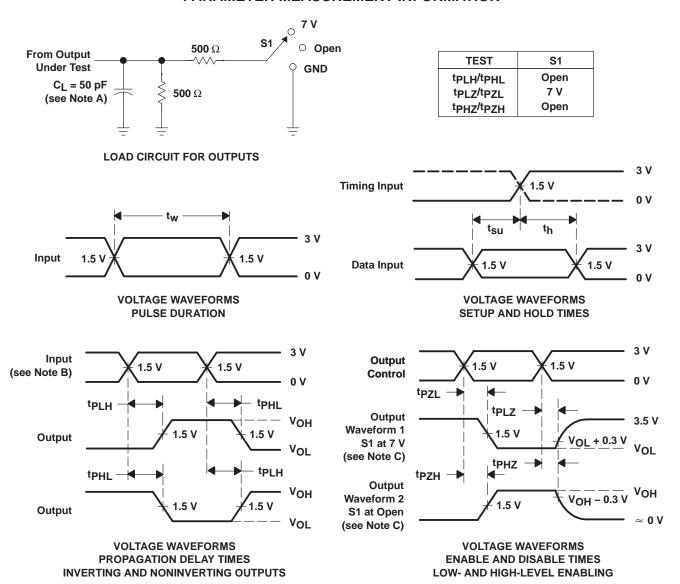
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT5400		SN74ABT5400		UNIT
	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH		V	2	4.5	5.7	2	6.7	2	6.5	
^t PHL	D	Y	1.5	3.7	4.5	1.5	5.5	1.5	5.2	ns
^t PZH		V	2.5	5.7	6.6	2.5	8.6	2.5	8.5	
t _{PZL}	OE	Y	2	4.4	5.5	\2\cdot\	6.9	2	6.8	ns
^t PHZ	ŌĒ	V	1.5	3.6	4.4	1.5	5.5	1.5	5.2	20
t _{PLZ}		l [†]	1.5	4.2	5.4	1.5	7.4	1.5	6.9	ns



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT5400DW	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI
SN74ABT5400DWR	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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